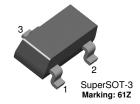


# **MMBF5434**

### **N-Channel Switch**

- · This device is designed for digital switching applications where very low on resistance is mandatory.
- Sourced from Process 58.



1. Drain 2. Source 3. Gate

# **Absolute Maximum Ratings \*** T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{DG}$	Drain-Gate Voltage	25	V
$V_{GS}$	Gate-Source Voltage	-25	V
I <sub>GF</sub>	Forward Gate Current	10	mA
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 ~ +150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
   These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

# **Electrical Characteristics** $T_A=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Charac	teristics		•		•
V <sub>(BR)GSS</sub>	Gate-Source Breakdwon Voltage	$I_{G} = -1.0 \mu A, V_{DS} = 0$	-25		V
I <sub>GSS</sub>	Gate Reverse Current	$V_{GS} = -15V, V_{DS} = 0$		200	nA
V <sub>GS</sub> (off)	Gate-Source Cutoff Voltage	V <sub>DS</sub> = 5.0V, I <sub>D</sub> = 3.0nA	-1.0	-4.0	V
I <sub>D</sub> (off)	Drain Cutoff Voltag	V <sub>DS</sub> = 5.0, V <sub>GS</sub> = -10V		200	pА
On Charac	teristics		•		•
I <sub>DSS</sub>	Zero-Gate Voltage Drain Current *	V <sub>DS</sub> = 15V, I <sub>GS</sub> = 0	30		mA
r <sub>DS</sub> (on)	Drain-Source On Resistance	$V_{DS} = 0, I_{D} = 10 \text{mA}$		10	Ω
Small Sign	al Characteristics		•		•
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 0, V <sub>GS</sub> = 10V, f = 1.0MHz		30	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	V <sub>DS</sub> = 0, V <sub>GS</sub> = 10V, f = 1.0MHz		15	pF

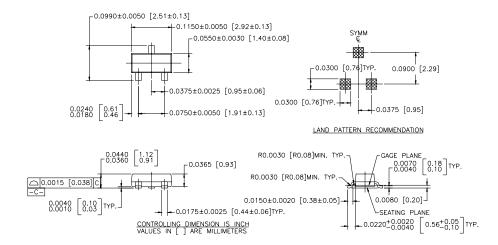
<sup>\*</sup> Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2.0%

Thermal Characteristics T <sub>A</sub> =25°C unless otherwise noted			
Symbol	Parameter	Max.	Units
$P_{D}$	Total Device Dissipation Derate above 25°C	350 2.8	mW mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	556	°C/W

<sup>\*</sup> Device mounted on FR-4 PCB 1.6"×1.6"×0.06"

# **Package Dimensions**

# SuperSOT-3



Dimensions in Millimeters

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EcoSPARK™	GTO™	MSX™	QT Optoelectronics™	TinyLogic <sup>®</sup>
E <sup>2</sup> CMOS <sup>TM</sup>	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	I <sup>2</sup> C <sup>TM</sup>	OCXTM	RapidConfigure™	UHC™
Across the board.	. Around the world.™	OCXPro™	RapidConnect™	UltraFET®
The Power Franchise™		OPTOLOGIC <sup>®</sup>	SILENT SWITCHER®	VCX™
Programmable Ad	ctive Droop™	OPTOPLANAR™	SMART START™	

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### **Definition of Terms**

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